

CLAIMS:

What is claimed is:

1 1. A method of forming a press-fit integrated chip package
2 comprising forming a laminate base structure having plated
3 through holes for introducing press-fit elements, forming a
4 laminate cover structure providing very fine conducting paths and
5 having a top mounting plane for mounting chips, and forming a
6 hybrid structure comprised of said laminate surface structure and
6 said laminate cover structure.

1 2. A method of forming a press-fit integrated chip package
2 comprising forming a laminate base structure having plated
3 through holes for introducing press-fit elements, forming a
4 laminate cover structure providing very fine conducting paths and
5 having a top mounting plane for mounting chips, and forming a
6 sandwich structure being comprised of said laminate surface
7 structure and said laminate cover structure, whereby said
8 structures are subsequently mechanically and electrically
9 conductive connected to each other.